

C1812C223GATACTU

Aliases (C1812C223GATAC7800) SMD Comm X8G HT150C, Ceramic, 0.022 uF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

1000

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

		Specifications	
	1812	Capacitance	0.
	4.5mm +/-0.3mm	Measurement Condition	11
	3.2mm +/-0.3mm	Tolerance	2
	1mm +/-0.10mm	Voltage DC	2
	2.3mm MIN	Dielectric Withstanding Voltage	6
	0.6mm +/-0.35mm	Temperature Range	-5
		Temp. Coefficient	Х
tions		Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30
	T&R, 180mm, Plastic Tape		

Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	2%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	45.4545 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions Chip Size

Packaging Specificat

Packaging Quantity

Packaging

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